

Advanced Packaging Workshop 2023

IEEE EPS Malaysia and IEEE Malaysia Section hosted a highly successful Advanced Packaging Workshop on two separate occasions, on the 17th of October in Bangi, and on the 19th of October in Penang, covering the southern and northern regions of Malaysia. This event, with jointly supported by IEEE Malaysia Section of Professional Activities and Industrial Relations (PAIR), attracted a substantial turnout, with over 200 participants hailing from various prominent organizations, including NXP, onsemi, Intel, Micron, ST Microelectronics, University of Malaya and more.

The workshop featured the invaluable insights and expertise of IEEE EPS distinguished lecturers, Dr. Tanja Braun and Jan Vadarman. They presented the latest advancements in packaging technology within the industry and shed light on emerging trends, particularly within the realm of automotive applications. Their informative and engaging presentations were met with enthusiasm and interest from the participating engineers. The positive feedback received from the attendees underlined the workshop's success, reflecting the value and relevance of the information shared. This event not only provided a platform for knowledge exchange and networking but also served as a testament to the commitment of IEEE EPS Malaysia in promoting education and advancements in the field of electronic packaging. It's evident that the workshop was well-received and contributed to the professional growth and development of the participants, further fostering innovation and progress in the industry.



Sharing of latest technology in advance packaging and automotive packaging trend



Token of appreciation to Distinguished Lecturer from IEEE EPS MALAYSIA past Chairlady Dr Tan Yik Yee



Q&A session – participants eager to get more information with latest trend.

Women in Engineering Panel Discussion

The "Empowering Women in Engineering" panel discussion, held in conjunction with the Advanced Packaging Workshop, brought together prominent figures from both the semiconductor industry and academia. During this interactive event, these accomplished individuals shared their experiences, struggles, motivations, and words of advice with the attendees, with a focus on empowering women in engineering.

One particularly inspiring story highlighted the profound impact of everyday work and innovation in the semiconductor industry. The narrative revolved around a young lady who was a daughter of a senior director of package development, she was involved in a severe car accident. Despite the vehicle being completely wrecked, the young woman miraculously emerged from the incident unharmed. The reason for her safety could be attributed to the reliable airbag sensor, which functioned flawlessly in that critical split second, protecting her from harm.

This story served as a powerful reminder of the importance of the work undertaken in the semiconductor industry. It underscored how the cutting-edge technology and innovation in this field can have a direct and life-saving impact on people's lives. It provided a tangible example of how engineers and scientists can make a real difference in the world by developing and improving crucial safety technologies. It also emphasized the significance of encouraging and empowering women to excel in engineering, as their contributions can have a far-reaching and positive effect on society.



Motivating and inspiring "Women in Engineering" panel discussion

IEEE EPS MALAYSIA extend our heartfelt gratitude to the esteemed panelists for their insightful contributions during the "Empowering Women in Engineering" session.



**Olivia Ng,
Operation Director,
STMicroelectronics**



**Dr Hafisoh Ahmad,
Senior Lecturer,
Taylor University**



**Dr Eu Poh Leng,
Senior Director,
NXP**



**Jan Vardaman,
President and Founder,
TechSearch International Inc**



**Rozalia Beica,
CSO & VP,
AT&S**



**Dr Tanja Braun,
Group Manager
Fraunhofer IZM**



**Ir Dr Banu Poobalan,
Senior Lecturer,
Universiti Malaysia Perlis**